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L Number	Hits	Search Text	DB	Time stamp
1	126		USPAT;	2003/07/07 10:01
•	120	pad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or		
		layer)		
2	0	438/14,15,762,763.ccls. and (integrated	USPAT;	2003/07/07 10:02
		adj circuit) and (contact adj pad) and	US-PGPUB;	
		((under adj bump adj metallurgy) or ubm)	EPO; JPO;	
	20	and (solder) and (wire) and (barrier)	DERWENT USPAT;	2003/07/07 10:03
3	32	(integrated adj circuit) and (contact adj	US-PGPUB;	2003/07/07 10.03
		<pre>pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and</pre>	EPO; JPO;	
		(barrier) and (lead)	DERWENT	
l <u> </u>	6039	(integrated adj circuit) and (contact adj	USPAT;	2003/01/30 15:08
	0033	pad) and (under adj bump adj region or	US-PGPUB;	
		layer)	EPO; JPO;	
1			DERWENT	
1 -	0	(integrated adj circuit) and (contact adj	USPAT;	2003/01/30 15:10
		pad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bomds)	DERWENT	2002/01/20 15 15
-	184	(integrated adj circuit) and (contact or	USPAT;	2003/01/30 15:15
]		output/input adj pads) and (under adj bump	US-PGPUB;	
]		adj region or layer) and (solder adj	EPO; JPO; DERWENT	,
]	118	bonds) and (wire adj bonds) (integrated adj circuit) and (contact adj	USPAT;	2003/01/31 10:15
-	118	pad) and (under adj bump adj region or	US-PGPUB;	2003/01/31 10:13
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds)	DERWENT	:
_	118	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31 10:25
		pad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
	1	layer) and (passivation adj region or		
	_	layer)		2002/06/10 15.27
-	0	"09888674" and (barrier)	USPAT; US-PGPUB;	2003/06/19 15:37
j			EPO; JPO;	
			DERWENT	
_	0	"09888674" and (barrier)	USPAT;	2003/06/20 10:14
. –		05000074 did (5011101)	US-PGPUB;	
		_	EPO; JPO;	
			DERWENT	
_	0	"09/888674" and (barrier)	USPAT;	2003/01/31 11:45
			US-PGPUB;	
			EPO; JPO;	
		l	DERWENT	2002/07/03 00 50
-	118	(integrated adj circuit) and (contact adj	USPAT;	2003/07/07 09:59
		pad) and (under adj bump adj region or	US-PGPUB; EPO; JPO;	
		layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or		
		layer)	1	
l _	۰ ا	1 -	USPAT;	2003/01/31 12:24
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	
	1	or ubm) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier) and (passivation)	DERWENT	
-	0		USPAT;	2003/01/31 12:25
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	
		or ubm) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier)	DERWENT	2002/01/21 12:25
-	4		USPAT;	2003/01/31 12:26
		pad) and ((under adj bump adj metallurgy)	US-PGPUB; EPO; JPO;	
		or ubm) and (solder) and (wire adj bonds) and (barrier)	DERWENT	
1_	28		USPAT;	2003/02/01 15:10
-	28	pad) and ((under adj bump adj metallurgy)	US-PGPUB;	-555, 52, 52 15.10
		or ubm) and (solder) and (wire) and	EPO; JPO;	
	1	(barrier)	DERWENT	
	L	, , ,,	<u> </u>	· ·

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-	118		USPAT;	2003/01/31 15:38
		pad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or		
	23	layer) (integrated adj circuit) and (contact adj	USPAT;	2003/07/07 10:03
_	23	pad) and ((under adj bump adj metallurgy)	US-PGPUB;	2003,01,01
ļ į	!	or ubm) and (solder) and (wire) and	EPO; JPO;	
	ŀ	(barrier) and (lead)	DERWENT	
_	l ol	438/15.ccls. and (integrated adj circuit)	USPAT;	2003/05/30 18:38
		and (contact adj pad) and ((under adj bump	US-PGPUB;	
		adj metallurgy) or ubm) and (solder) and	EPO; JPO;	i
1		(wire) and (barrier)	DERWENT	
-	0	438/15,762,763.ccls. and (integrated adj	USPAT;	2003/07/07 10:01
		circuit) and (contact adj pad) and ((under	US-PGPUB;	
		adj bump adj metallurgy) or ubm) and	EPO; JPO; DERWENT	
	4	(solder) and (wire) and (barrier) 257/737.ccls. and (integrated adj circuit)	USPAT;	2003/05/30 18:41
-	4	and (contact adj pad) and ((under adj bump	US-PGPUB;	2003/03/30 10.41
		adj metallurgy) or ubm) and (solder) and	EPO; JPO;	
		(wire) and (barrier)	DERWENT	
-	27	(integrated adj circuit) and (contact adj	USPAT;	2003/05/30 18:01
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	
		or ubm) and (solder) and (wire) and	EPO; JPO;	
		(barrier) and (lead)	DERWENT	0000/05/00 10 11
-	0	438/15.ccls. and (integrated adj circuit)	USPAT;	2003/05/30 18:44
1	·	and (contact adj pad) and ((under adj bump	US-PGPUB; EPO; JPO;	•
		adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	DERWENT	
_	123	(integrated adj circuit) and (contact adj	USPAT;	2003/05/30 18:41
	123	pad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or	1	
		layer)		0000 (05 (20 10 51
-	4		USPAT;	2003/05/30 18:51
		and (contact adj pad) and ((under adj bump	US-PGPUB; EPO; JPO;	
		adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	DERWENT	
_	0	438/15.ccls. and (integrated adj circuit)	USPAT;	2003/05/30 18:45
		and (contact adj pad) and ((under adj bump	US-PGPUB;	
		adj metallurgy) or ubm) and (solder) and	EPO; JPO;	
		(wire) and (barrier)	DERWENT	
-	8	257/738.ccls. and (integrated adj circuit)	USPAT;	2003/05/30 19:03
		and (contact adj pad) and ((under adj bump	US-PGPUB;	
		adj metallurgy) or ubm) and (solder) and	EPO; JPO;	
		(wire) and (barrier)	DERWENT USPAT;	2003/05/30 19:04
-	4	257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump	US-PGPUB;	2003/03/30 19.04
		adj metallurgy) or ubm) and (solder) and	EPO; JPO;	
		(wire) and (barrier)	DERWENT	
_	36		USPAT;	2003/05/31 11:42
		pad) and (barrier adj layer) and (nickel	US-PGPUB;	
		adj barrier) and (solder adg layer)	EPO; JPO;	
			DERWENT	2002/05/21 11 12
-	4		USPAT;	2003/05/31 11:43
1		pad) and (barrier adj layer) and (nickel	US-PGPUB; EPO; JPO;	
		adj barrier) and (solder adj layer)	DERWENT	
_	۱ ،	"6221682" and gold	USPAT;	2003/06/19 13:21
	ı		US-PGPUB;	
			EPO; JPO;	1
			DERWENT	
-	0	"20010011764" and gold	USPAT;	2003/06/19 13:52
			US-PGPUB;	
			EPO; JPO;	
		#20010011764#	DERWENT USPAT;	2003/06/19 13:52
-	2	"20010011764"	US-PGPUB;	2003/00/19 13.32
			EPO; JPO;	İ
			DERWENT	
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			_	
-	0	"6441487" and (gold)	USPAT;	2003/06/19 15:37
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_ i	9	"5234149" and (gold)	USPAT;	2003/06/19 15:38
		0201215 0110 (3020)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
l <u> </u>	6	"5234149" and (under adj bump)	USPAT;	2003/06/19 19:18
	Ů	Jestitis and tander and samp,	US-PGPUB;	2000, 00, 20 20 20
			EPO; JPO;	
			DERWENT	
	ا م	5234149.pn. and (under adj bump)	USPAT;	2003/06/19 17:48
-	١	J254149.pm. and (under ad) bump)	US-PGPUB;	2003,00,13 110
			EPO; JPO;	
			DERWENT	
	1	"20010011764" and (under adj bump)	USPAT;	2003/06/19 19:18
-	1	"20010011764" and (under ad) bump)	US-PGPUB;	2003/00/19 19.10
			EPO; JPO;	
		"00010011TG4"	DERWENT	2003/06/19 19:19
-	1	"20010011764" and (electroplating)	USPAT;	2003/06/19 19:19
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT	0000/06/00 10 15
-	10	"5234149" and (reflow\$3)	USPAT;	2003/06/20 10:15
			US-PGPUB;	
	}		EPO; JPO;	
			DERWENT	
-	0	5234149.pn. and (reflow\$3)	USPAT;	2003/06/20 10:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	1	20010011764.pn. and (reflow\$3)	USPAT;	2003/06/20 10:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	1	20010011764.pn. and (lead)	USPAT;	2003/06/20 10:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	1	20010011764.pn. and (reflow\$3)	USPAT;	2003/06/20 11:05
		<u> </u>	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	n	20010011764.pn. and (selective adj	USPAT;	2003/06/20 11:05
		electroplating)	US-PGPUB;	
			EPO; JPO;	
1	[DERWENT	
1	I	1	1	1